

## **SRAM**

# **512K x 8 SRAM**

WITH OUTPUT ENABLE

#### **FEATURES**

OPTIONS

- High speed: 20, 25, 35 and 55ns
- High-performance, low-power, CMOS double-metal process

MARKING

- Single +5V ±10% power supply
- Easy memory expansion with CE and OE options
- All inputs and outputs are TTL compatible
- Fast Output Enable access time: 8ns

OI IIOI10	MARKINI
Timing	
20ns access	<b>-2</b> 0
25ns access	<b>-2</b> 5
35ns access	-35
55ns access	-55
Packages	
TH .1 00T (400 11)	TNI

Packages
 Plastic SOJ (400 mil)
 DJ

 Available in ceramic packages tested to meet military specifications. Please refer to Micron's Military Data Book.

• 2V data retention L

• Temperature
Industrial (-40°C to +85°C) IT
Automotive (-40°C to +125°C) AT
Extended (-55°C to +125°C) XT

### PIN ASSIGNMENT (Top View)

**32-Pin SOJ** (E-11)

A18 [	1	32	Vcc
A16 [	2	31	A15
A14 [	3	30	A17
A12 [	4	29	D WE
A7 [	5	28	A13
A6 [	6	27	A8
A5 [	7	26	A9
A4 [	8 _	25	A11
A3 [	9	24	OE
A2 [	10	23	A10
A1 [	11	22	CE
A0 [	12	21	DQ8
DQ1 [	13	20	DQ7
DQ2 [	14	19	DQ6
DQ3 [	15	18	DQ5
Vss [	16	17	DQ4

#### **GENERAL DESCRIPTION**

The Micron SRAM family employs high-speed, low-power CMOS designs using a four-transistor memory cell. Micron SRAMs are fabricated using double-layer metal, double-layer polysilicon technology.

For flexibility in high-speed memory applications, Micron offers chip enable  $(\overline{\text{CE}})$  capability. This enhancement can place the outputs in High-Z for additional flexibility in system design.

Writing to this device is accomplished when write enable  $(\overline{WE})$  and  $\overline{CE}$  inputs are both LOW. Reading is accomplished when  $\overline{WE}$  remains HIGH while output enable  $(\overline{OE})$  and  $\overline{CE}$  go LOW. The device offers a reduced power standby mode when disabled. This allows system designers to achieve their low standby power requirements.

All devices operate from a single +5V power supply and all inputs and outputs are fully TTL compatible.